



# SOD523

plastic surface-mounted package; 2 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SOD523
<b>Package type industry code</b>	SOD523
<b>Package style descriptive code</b>	SOD (small outline diode)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEITA package outline code</b>	SC-79
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.15	-	1.2	1.25	mm
E	package width	0.75	-	0.8	0.85	mm
A	seated height	0.58	-	0.6	0.65	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

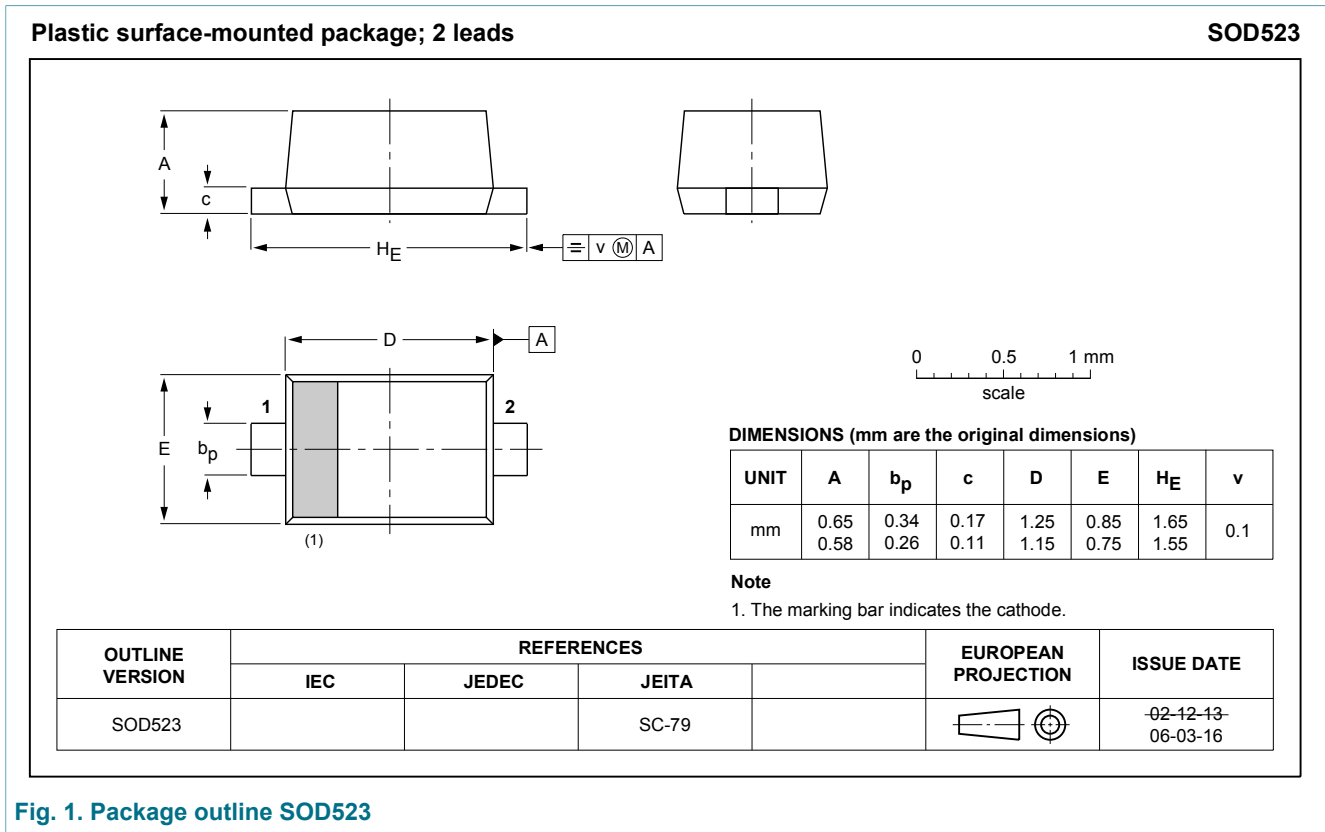


Fig. 1. Package outline SOD523

## 3. Soldering

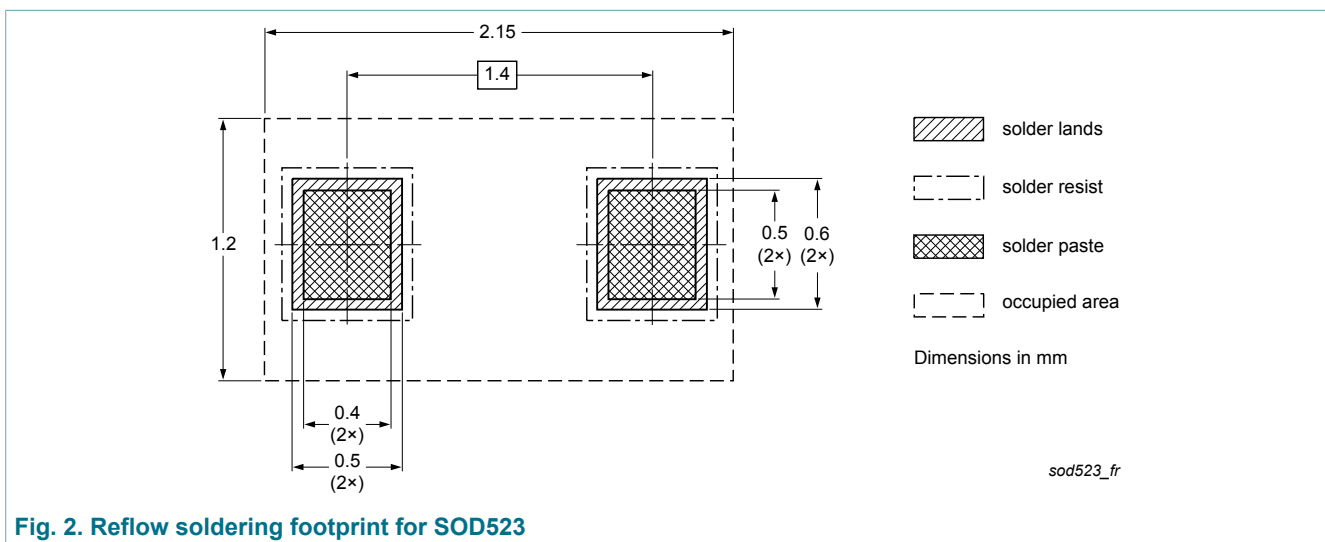


Fig. 2. Reflow soldering footprint for SOD523

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	2
4. Legal information.....	3

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